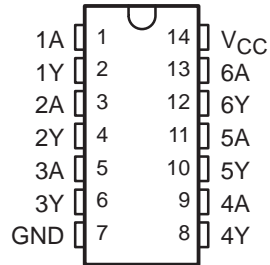
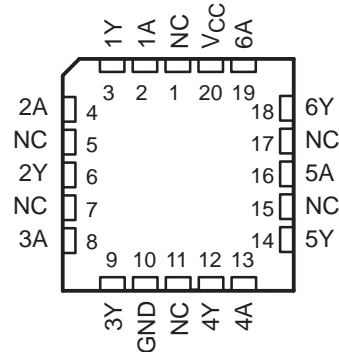


- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 7 ns at 5 V

SN54AC04 . . . J OR W PACKAGE
SN74AC04 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AC04 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'AC04 devices contain six independent inverters. The devices perform the Boolean function $Y = \bar{A}$.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AC04N	SN74AC04N
	SOIC – D	Tube	SN74AC04D	AC04
		Tape and reel	SN74AC04DR	
	SOP – NS	Tape and reel	SN74AC04NSR	AC04
	SSOP – DB	Tape and reel	SN74AC04DBR	AC04
	TSSOP – PW	Tube	SN74AC04PW	AC04
Tape and reel		SN74AC04PWR		
–55°C to 125°C	CDIP – J	Tube	SNJ54AC04J	SNJ54AC04J
	CFP – W	Tube	SNJ54AC04W	SNJ54AC04W
	LCCC – FK	Tube	SNJ54AC04FK	SNJ54AC04FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54AC04, SN74AC04 HEX INVERTERS

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logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54AC04		SN74AC04		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	6	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 4.5 V	3.15		3.15		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V	0.9		0.9		V
		V _{CC} = 4.5 V	1.35		1.35		
		V _{CC} = 5.5 V	1.65		1.65		
V _I	Input voltage		0	V _{CC}	0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V	−12		−12		mA
		V _{CC} = 4.5 V	−24		−24		
		V _{CC} = 5.5 V	−24		−24		
I _{OL}	Low-level output current	V _{CC} = 3 V	12		12		mA
		V _{CC} = 4.5 V	24		24		
		V _{CC} = 5.5 V	24		24		
Δt/Δv	Input transition rise or fall rate		8		8		ns/V
T _A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	3 V	2.9	2.99		2.9		2.9		V
		4.5 V	4.4	4.49		4.4		4.4		
		5.5 V	5.4	5.49		5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.46		
		4.5 V	3.86			3.7		3.76		
	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		
		5.5 V				3.85				
V _{OL}	I _{OL} = 50 µA	3 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		5.5 V		0.001	0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44	
		5.5 V				1.65				
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	µA
		5.5 V			2		40		20	µA
C _i	V _I = V _{CC} or GND			2.8						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.5	4.5	9	1	11	1	10	ns
t _{PHL}			1.5	4.5	8.5	1	10	1	9.5	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.5	4	7	1	8.5	1	7.5	ns
t _{PHL}			1.5	3.5	6.5	1	7.5	1	7	

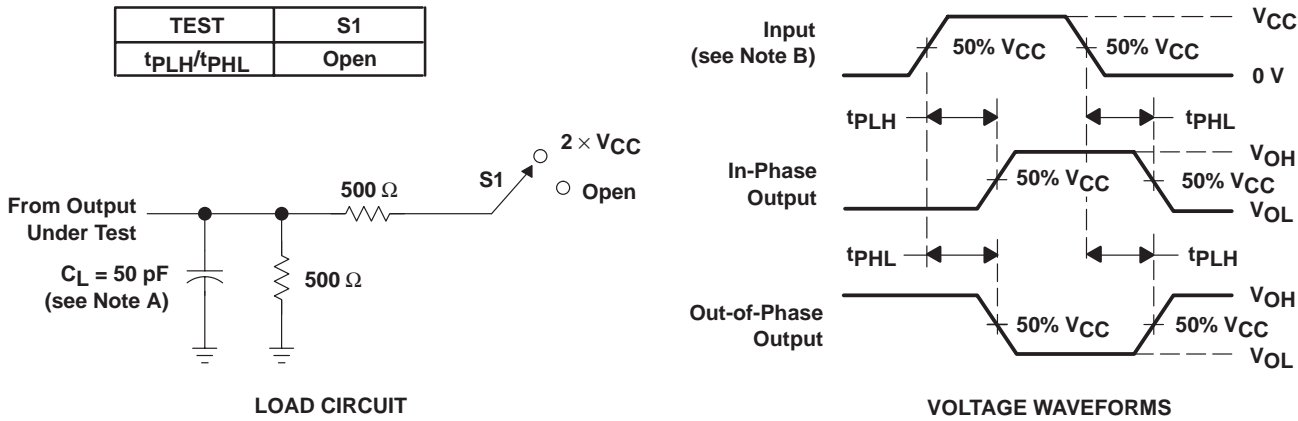
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	C _L = 50 pF, f = 1 MHz	45	pF

SN54AC04, SN74AC04
HEX INVERTERS

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87609012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
5962-8760901CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
5962-8760901DA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type
SN74AC04D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74AC04DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC04NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC04NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AC04PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC04PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AC04FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AC04J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SNJ54AC04W	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered

at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



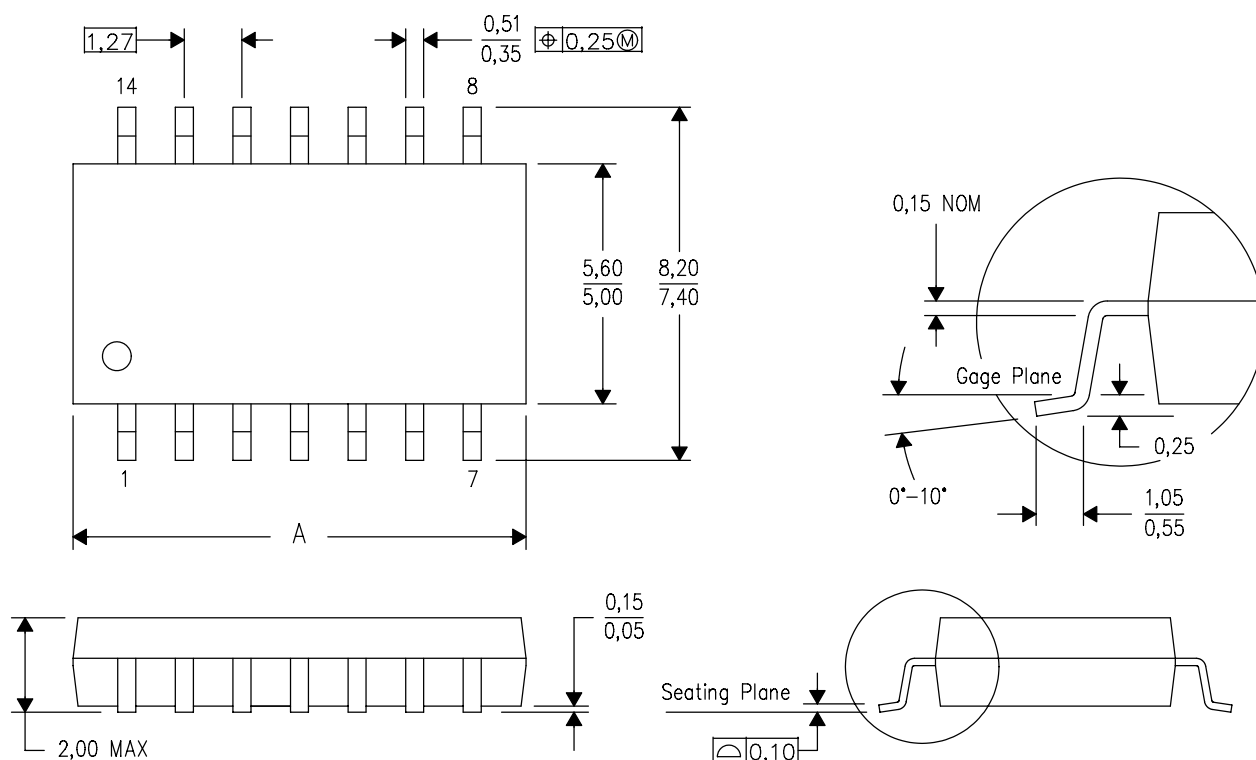
4040047-3/F 07/2004

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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